



[Return to: CBR Home](#) | [Systems & Networks](#) | [Networking](#)

Sony, Tokyo Tech join hands to bring low-power LSIs for wireless data transfer

■ [Networking News](#)

Select a Technology sector

CBR Staff Writer

Published 20 February 2012

Enables data transfer at a rate of 6.3 Gb/s

Sony Corporation together with the National University Corporation and Tokyo Institute of Technology have jointly developed a radio frequency LSI and a baseband LSI that enables millimetre-wave wireless data transfer at a rate of 6.3 Gb/s.

The technology was adopted for presentation at the International Solid-State Circuits Conference (ISSCC) to be held in San Francisco from February 19.

Sony said the millimetre-wave wireless data transfer technology realises both high-speed and low-power data transfer between mobile devices and its implementation will enable users to transmit and receive data at much higher speeds between mobile devices without the need for cable connections.

This technology will also enable users to access high-quality video streaming from a mobile device to a display.

Sony has designed the digital parts of the BB LSI and the development of the chip unit as a whole, while the Tokyo Institute of Technology designed the RF LSI and the analog parts of BB LSI.

Sony said the rate-14/15 Low-Density Parity-Check (LDPC) error-correcting code developed by it decreases the amount of redundant data that is required for error correction, which has enabled LDPC decoding at 6.3 Gb/s.

This LDPC code was proposed to the 60 GHz band millimetre-wave wireless communication standard IEEE 802.15.3c and employed in the standards.